



Fall 2023

Rev 7-21-23

#### IC Technology

#### **Transistors**

Dr Jeff Drobman

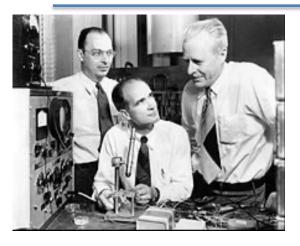
drjeffsoftware.com/classroom.html

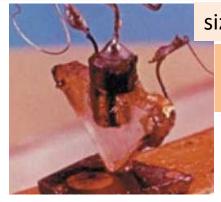
email | jeffrey.drobman@csun.edu



#### The Transistor







size =  $^1$  inch

#### **1947** ushered in the era of *Microelectronics*

A transistor is a semiconductor device used to amplify or switch electronic signals and electrical power. It is composed of semiconductor material usually with at least three terminals for connection to an external circuit. A voltage or current applied to one pair of the transistor's terminal



❖ 1947- Bipolar point/junction

❖ 1959- Planar bipolar [10]\*

❖ 1964- MOS (P-channel) [100]

❖ 1972- MOS (N-channel) [1,000]

**❖** 1978- CMOS [4,000]

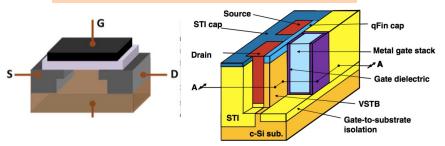
❖ 1990- sub-micron [10,000]

**\$** 2000- 100 nm [100,000]

**❖** 2011- FinFET [1,000,000]

\*no. of transistors

Transistors have been shrunk every 2 years according to *Moore's Law* 



\* size = 10 nm =  $4x10^{-7}$  inches

❖ yields → ~1M devices per cm²



#### **Viewing Transistors**



Quora

### How are billions of transistors compressed into a single chip? Can a transistor in the chip be seen with a microscope?



**Jeff Drobman**Works at Dr Jeff Software ⋅ Just now ⋅ ⑤

once a chip is complete, only the top few layers of metal interconnect are visible (unless etched away). a single transistor is way too small to be readily identified, as they are now as small as about 25–40 nm in overall size. note that a "5nm" node means that only the channel length is that small. the overall transistor size, and pitch, is more like 25–40 nm.



#### **Transistor Atoms**







Al Kordesch, Semiconductor Device Modeling

Answered Feb 1, 2019

How many atoms are in a typical transistor in a chip?

Short Answer: 49,000 atoms!

**Apple's iPhone XS uses 7 nanometer transistors.** So let's estimate how many atoms are in one of them. Excluding the connecting wires and other parts, I'm just going to calculate the size of the active part, the "channel" under the gate. The volume of the channel is about  $(7 \text{ nm long}) \times (7 \text{ nm deep}) \times (20 \text{ nm wide})$ . The atomic density of silicon is 5E+28 atoms per cubic meter. So let's go!

Number of atoms n = volume x density

 $n = (980E-27) \times (5E+28) = 49,000$ atoms.

Atomic radius = .111nm  $\rightarrow$  4.5 atoms/nm  $\rightarrow$  5/nm

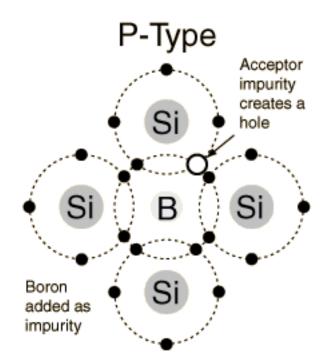
Cubic: 5x5x5 = 125 atoms/cu nm

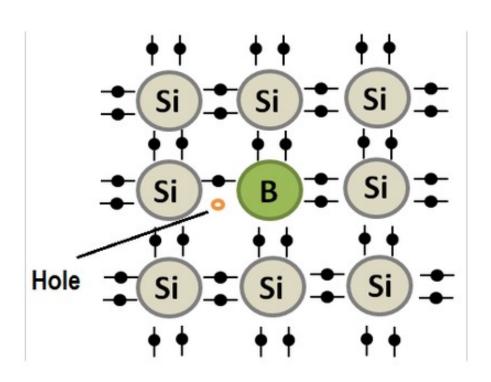
@7n: ~1000 cu nm



#### P-type Semi







(Source: Doped Semiconductors ☑)

- ❖ Majority carrier = Holes slow
- Electron Acceptor



#### IC Process & Interface



TTL compatible — 5V → 3V

#### **❖** Bipolar

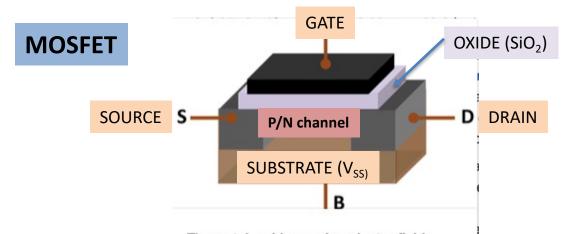
**5V** 

ightharpoonup RTL 
ightharpoonup DTL 
ightharpoonup TTL 
ightharpoonup Schottky TTL 
ightharpoonup LS TTL

1960 1965 1970 1975 1980 1985 1990 **♣** MOS **BiCMOS** 

 $\rightarrow$  PMOS $\rightarrow$ NMOS $\rightarrow$  CMOS $\rightarrow$  CMOS $(\overline{TTL} I/O)\rightarrow$  3.3V

 $5V \rightarrow 3V$ 

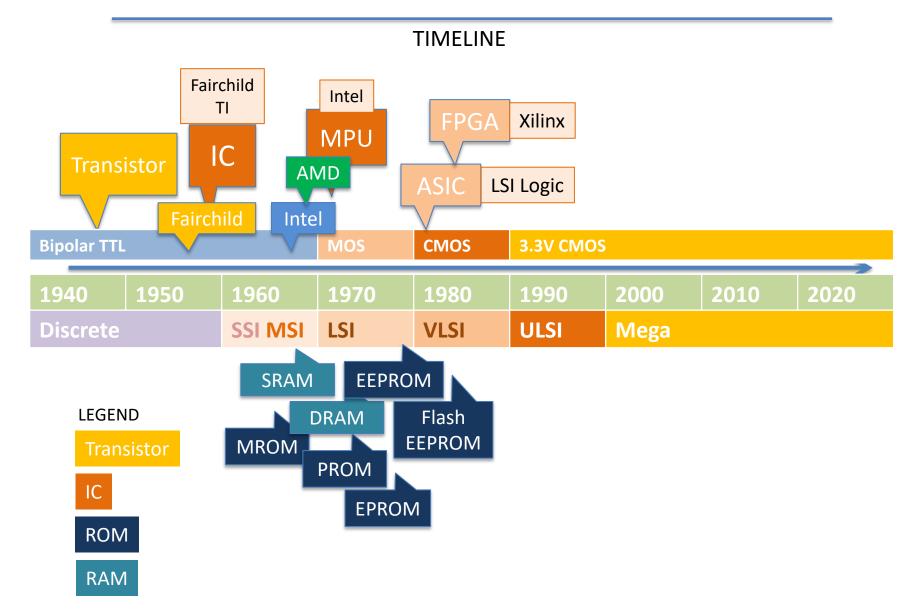


The metal-oxide-semiconductor fieldeffect transistor, also known as the metaloxide-silicon transistor, is a type of fieldeffect transistor that is fabricated by the controlled oxidation of a semiconductor, typically silicon. It has an insulated gate, whose voltage determines the conductive



#### **IC Technology**







#### Section



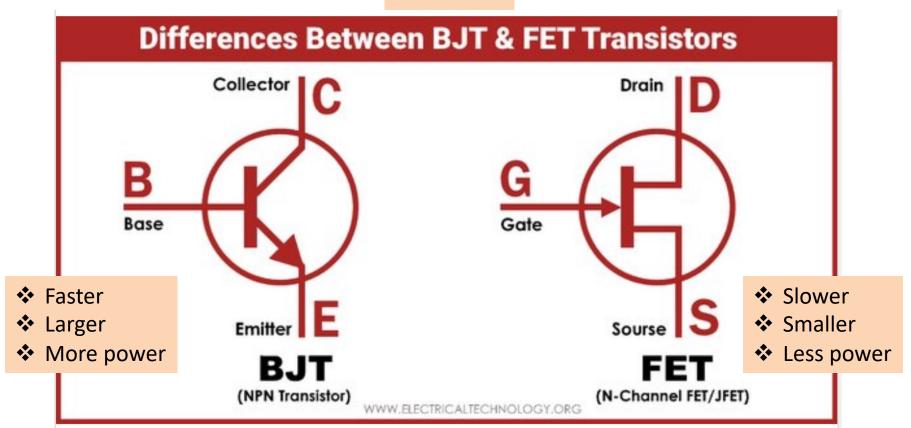
# Bipolar (BJT) Transistors



#### Bipolar/MOSFET Transistors



**Schematics** 

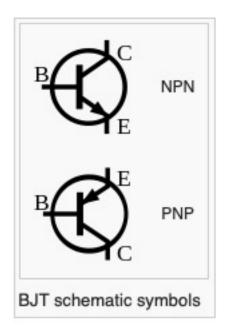


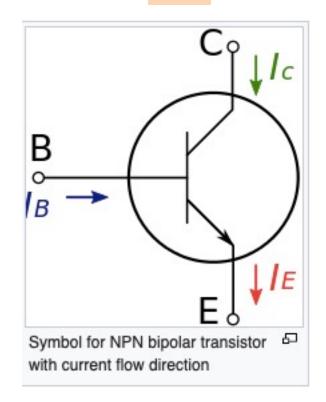
- Current flows opposite electrons (C->E, S->D)
- ❖ B, G are inputs (H/L)
- ❖ B, G voltages turn transistor ON/OFF
- Outputs (not shown) are tied to C, D





BJT





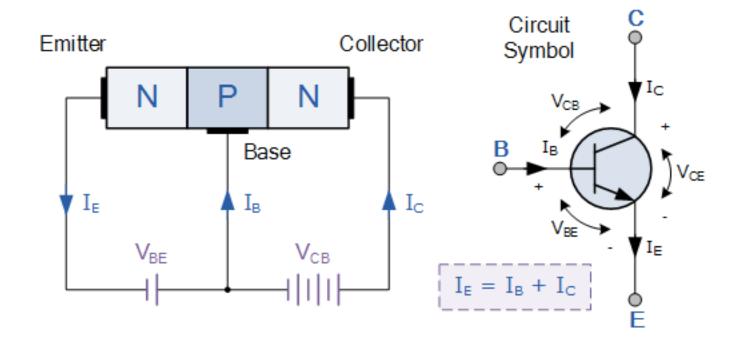


Typical individual BJT □ packages. From top to bottom: TO-3, TO-126, TO-92, SOT-23





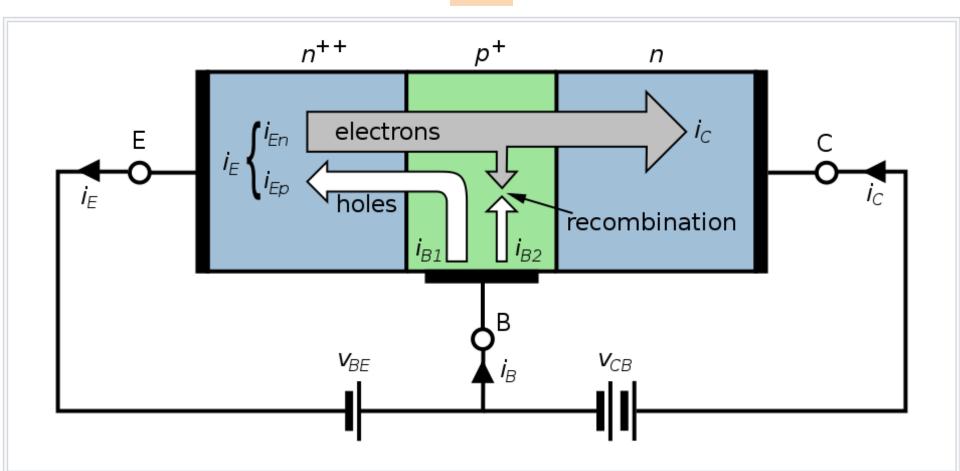
BJT







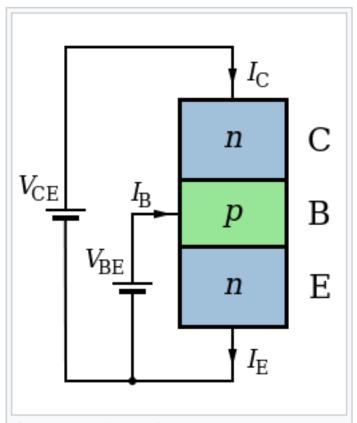
BJT -





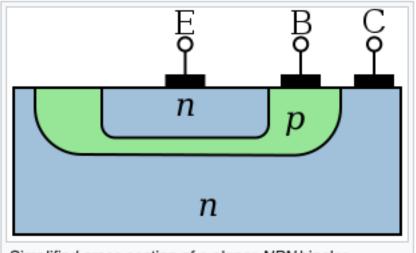


BJT



Structure and use of NPN transistor. Arrow according to schematic. **PLANAR** 

Structure [edit]



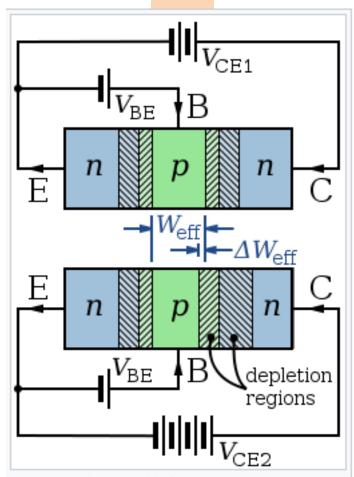
Simplified cross section of a planar NPN bipolar junction transistor



#### **Transistors**



BJT



Top: NPN base width for low collector-base reverse bias; Bottom: narrower NPN base width for large collector-base reverse bias. Hashed regions are depleted regions.

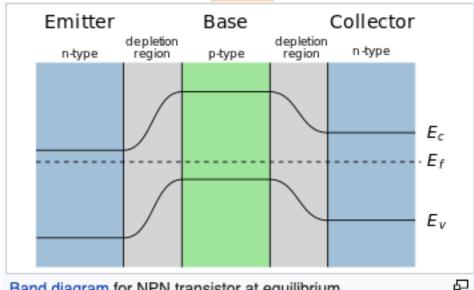
**Depletion Regions** 



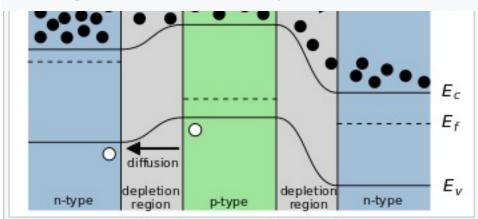
#### **Transistors**



**BJT** 



Band diagram for NPN transistor at equilibrium

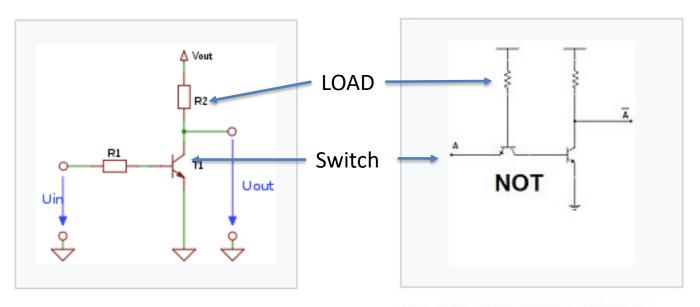


D Band diagram for NPN transistor in active mode, showing injection of electrons from emitter to base, and their overshoot into the collector



#### **BJT Gates**





NPN resistor-transistor logic

inverter

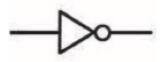
NPN transistor–transistor logic

TTL

inverter

RTL







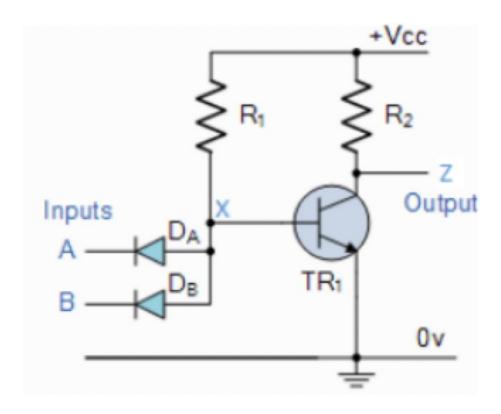
#### **BJT-DTL NAND Gate**



Quora\_

1T

A DTL NAND gate is pretty easy to build using a single NPN bipolar transistor and a diode for each input:





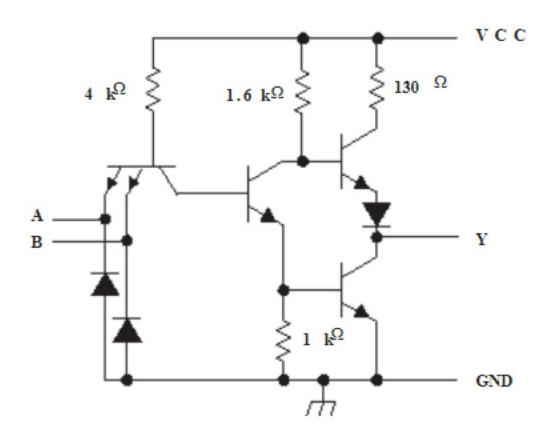
#### BJT-TTL NAND Gate



Quora\_

1T

Each gate in the original 7400 TTL quad 2-input NAND had four bipolar transistors, with the input having multiple emitters, one for each input with associated diodes:





#### Section



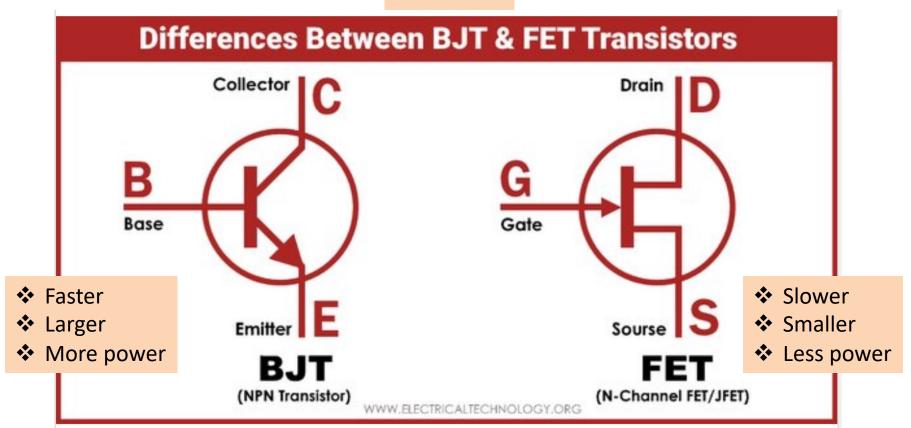
# MOS (FET) Transistors



#### Bipolar/MOSFET Transistors



**Schematics** 



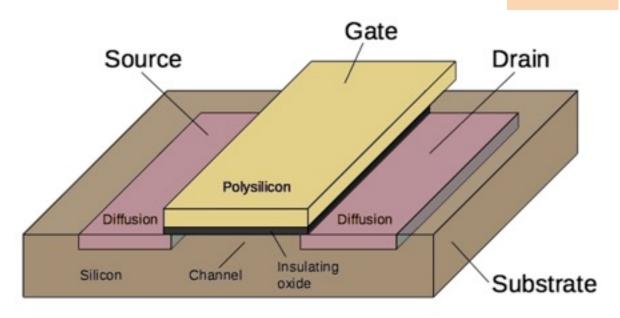
- Current flows opposite electrons (C->E, S->D)
- ❖ B, G are inputs (H/L)
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- Outputs (not shown) are tied to C, D



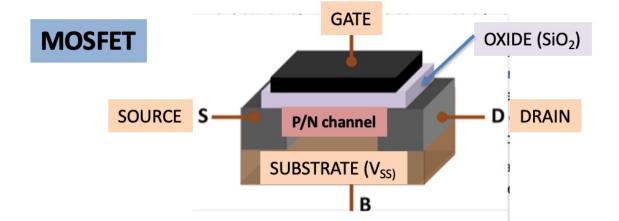
#### **MOS Transistor**



WikiSemi



Structure of a MOSFET in the integrated circuit.





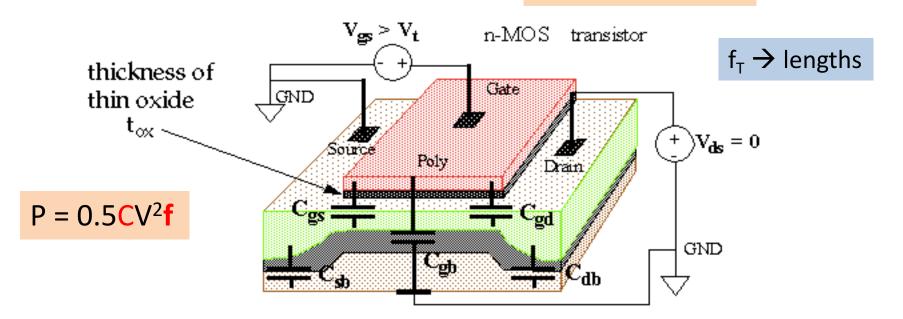
#### **MOS Transistors**



The channel will have a length (distance from one electrode to the other) and a width (imagine this diagram coming out of the screen). The electrodes have geometries. The gate doesn't always span the full width of the channel and is its own critical dimension.

The sizes of each of these things are critical dimensions. They all have an effect on the performance of the device because they will contribute parasitic capacitance and resistance.

Parasitic capacitances

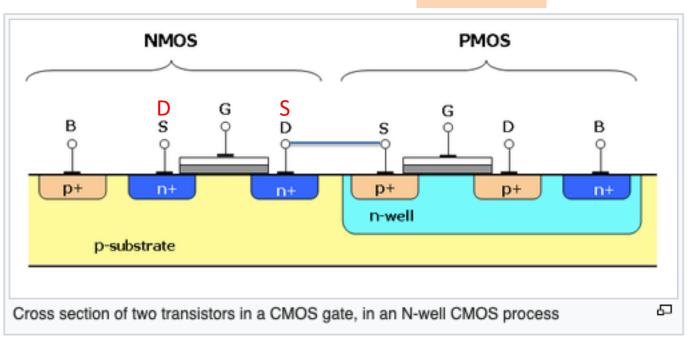


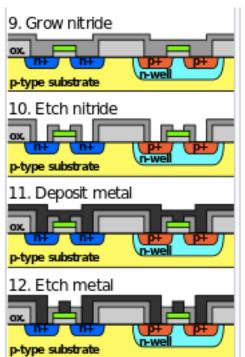


#### **CMOS** Transistors



#### **MOSFET**





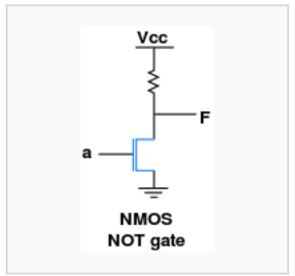
Last 4 steps

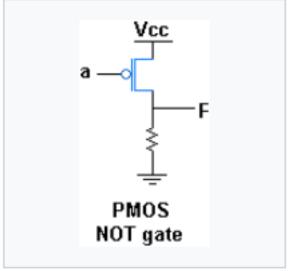


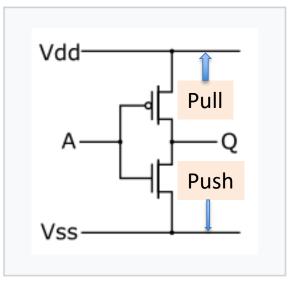
#### **MOS** Gates



**MOSFET** 





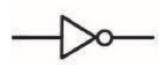


NMOS inverter

PMOS inverter

Static CMOS inverter

NOT



P/N Totem pole

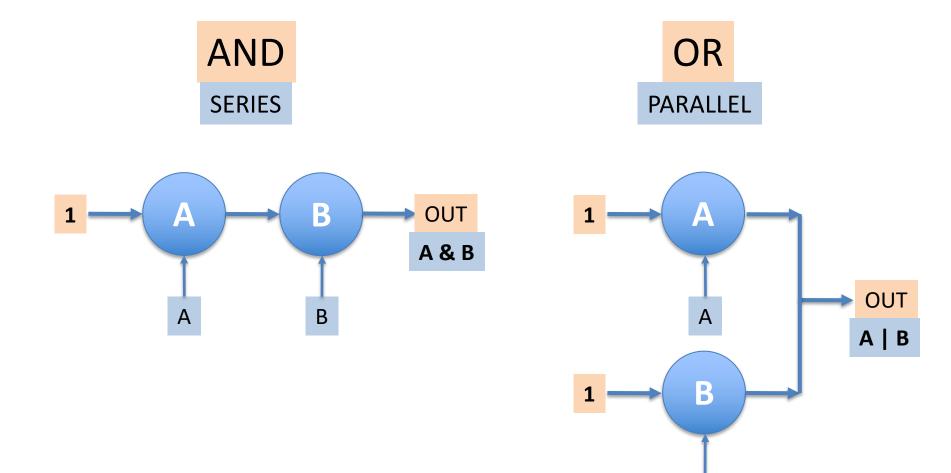
**C**MOS

Push-Pull



#### Logic Gates: AND, OR



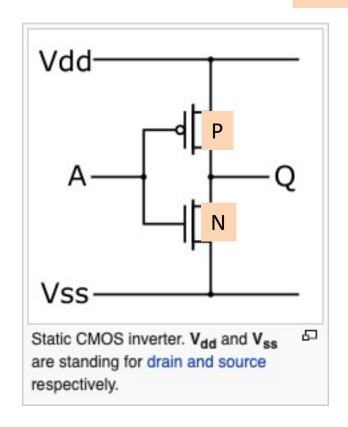


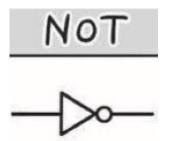


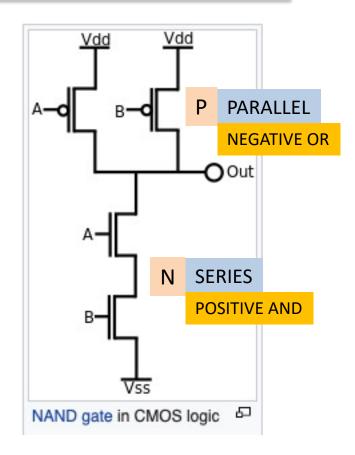
#### **CMOS** Gates

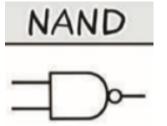


#### **MOSFET**







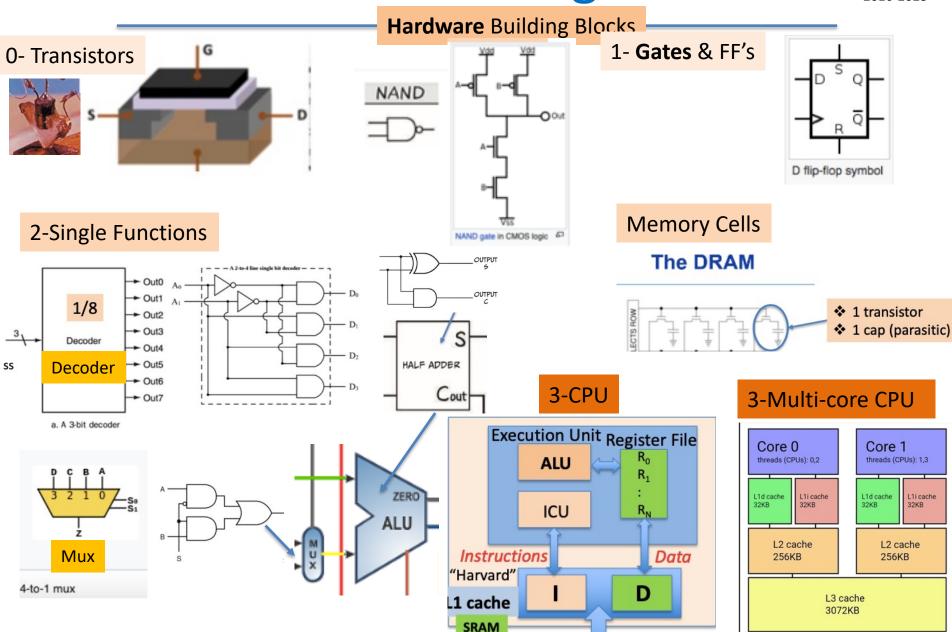




#### 3 Levels of Integration



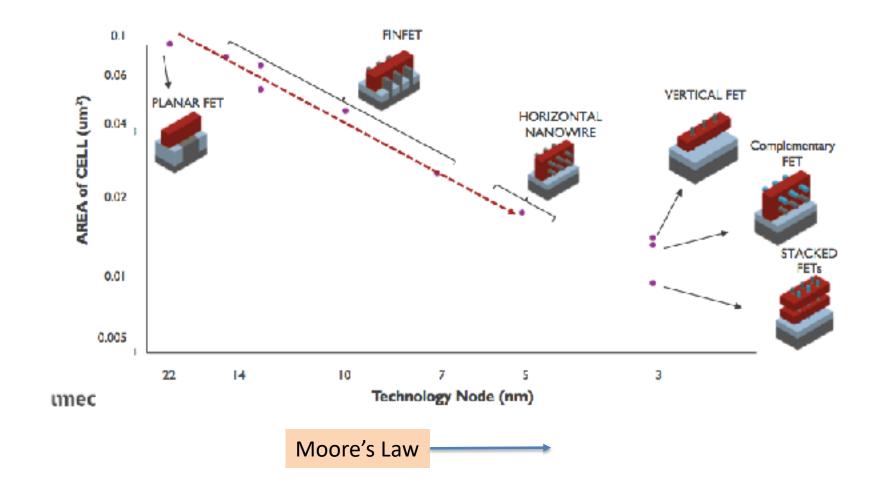
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#### **Transistor Processes**



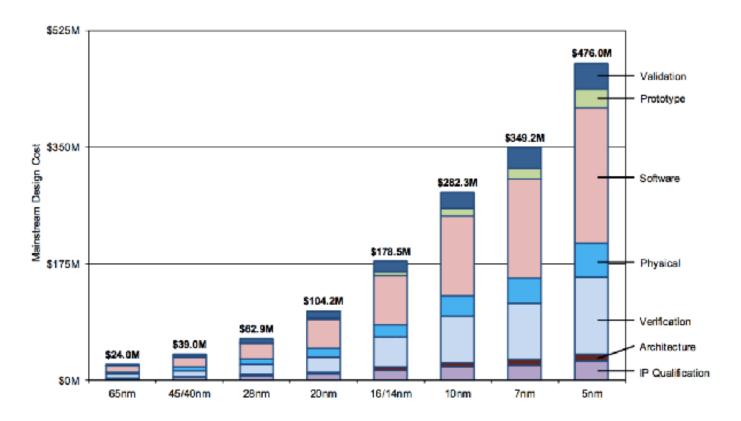




#### **Transistor Processes**



In the short run, there is nothing stopped chips from adopting 'smaller' nodes (3–1 nm) but by 2023–2025, the cost of development, equipment, tooling will become so high and FinFET scaling will plateau, meaning that alternative post-FinFET devices will have to developed to ensure that performance continues to scale.

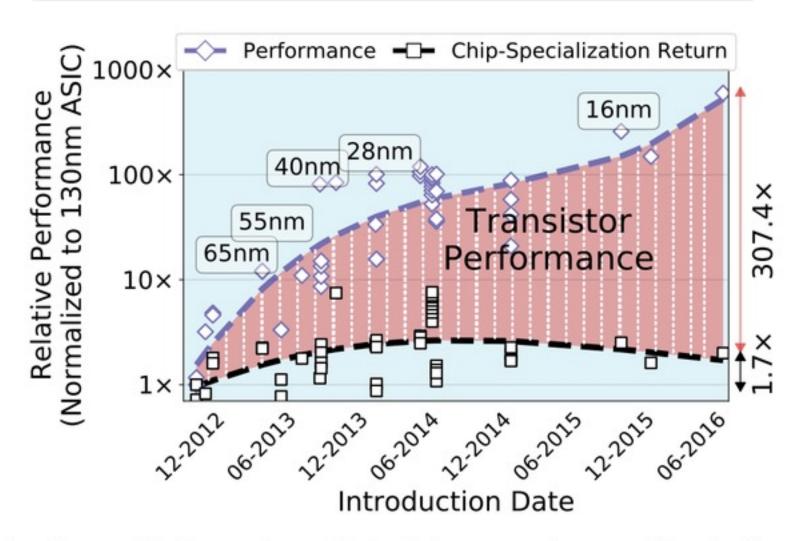


There are multiple concepts such as gate all around FETs (GAA-FETs) and FETs with horizonal nanowire being explored but none are currently viable for high volume IC.



#### Chip Specializations





On-chip specialization or microarchitctural changes merely account for a fraction of the performance gains.



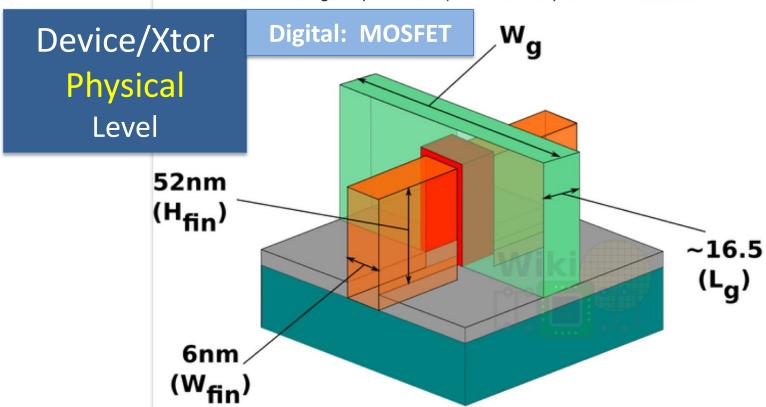
#### Chip Fab: FinFET



7 nm TSMC

What's a 5nm FinFET transistor look like?

Well... I didn't find a good pic for 5nm, but I found a pic for 7nm here: ☑



We can assume 5nm is slightly smaller on all axes.

The first thing to note is that the gate length ( $L_g$ ) is 16.5nm. The width of the gate will vary, but I am going to go out on a limb and guess it is no smaller than  $3W_{\rm fin}$ , or 18nm. And the overall structure is tall: 52nm plus another few nm



#### **MOSFET Evolution**



Device/Xtor
Physical
Level

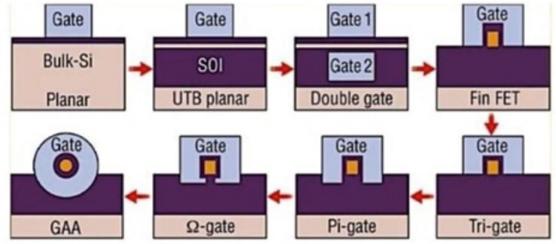
**Digital: MOSFET** 





### Nanoscale FinFET Technology for Circuit Designers

Alvin L.S. Loke, NXP





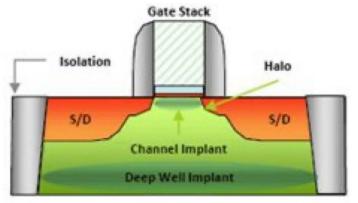
#### 3nm FinFET



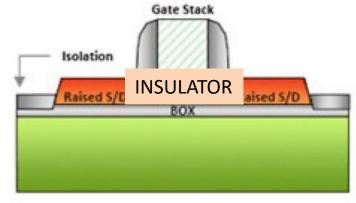
SOI

**Digital: MOSFET** 

Another possibility is to move back to Silicon on Insulator (SOI) with a modified FD-SOI MOSFET. These would use a channel made of something other than monocrystalline Silicon with the intention of engineering for a more constrained electron wave-function. [Sorry, it truly is impossible to talk modern semiconductors without invoking Quantum Mechanics at some point]







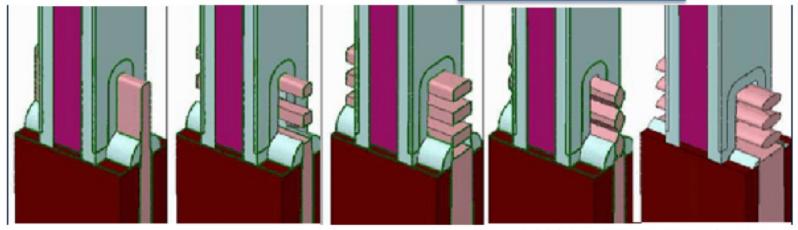
FD-SOI Device



#### 3nm FinFET



#### **Digital: MOSFET**



Ref: 8.C. Song, Qualcomm; V. Moroz, Synopsys

Traditional FinFET	Round/Square Wire	Horizontal Nanoslab/sheet/ multi-bridge channel	Hexagonal Nanowire	Nano-Ring
Three control surfaces	Four/All Around Control Surfaces Per Channel			

All around gates were believed essential to 7nm and beyond but 7nm was developed just fine on FinFETs and TSMC has demonstrated 3nm FinFET manufacturing as of 2020. Unfortunately, no "need" translates to limited development in HVM environments.